ABSTRACT OF THE DISCLOSURE

Disclosed is a multi-functioned wafer aligner comprising a multi-functioned unit performing a wafer centering operation, a wafer flat zone alignment, and a wafer damage detection, and a main processor deciding positions of the wafer centering operation and the wafer

5   flat zone alignment, and discriminating wafer damage, such as wafer breakage and wafer crack, by calculating an accumulated digital signal inputted from the multi-functioned unit.